

## Reliability Performance

### Reliability Experiment For Electrical

Test Item	Test Conditions	Standard Source
Humidity Test	+40°C±2°C, humidity of 90%±5% (Total 96 hours)	MIL-STD-202G Method 103B Test Condition B
High Temperature Test	1. Temperature : +125°C±2°C 2. Test time : 48±2 hrs	IEC 68-2 Test Condition B
Low Temperature Test	1. Temperature : -25°C±2°C 2. Test time : 48±2 hrs	IEC 68-2 Test Condition A
Thermal Shock	+125°C±5°C (30 minutes) ~ -55±5°C (30 minutes), temperature switch time : 5 minutes (Total 50 cycles) Wind speeds 10m/sec.	Reference MIL-STD-202G Method 107G Test Condition A-2
Life Test	+70°C±5°C (250 Hours)	Reference MIL-STD-202G Method 108A Test Condition B

### Reliability Experiment For Physical

Test Item	Test Conditions	Standard Source
Vibration Test	Frequency : 10-55-10 HZ, Amplitude : 1.5mm, Direction : X, Y, Z axes, each axis 2 hour (Total 6 hours)	MIL-STD-202G Method 201A
Solder Heat Resistance Test	IR / Convection Reflow : Peak Temp. 255°C~260°C for 3~5 Sec. in air, Through 2 Cycle. Temperature Ramp : +1~4°C/Sec.; Above 217°C, must keep 90 s-120 s.	Reference MIL-STD-202G Method 210F Test Condition K (Reflow)
Solder Ability Test	Soak in 245°C solder pot of 3~5 Sec., PAD must have 95% above coverage.	Reference J-STD-002D

### Typical RoHS Reflow Profile

